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(71) Applicant (for all designated States except US): ENTHONE INC. [US/US]; 350 Frontage Road, West Haven, CT 06516 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): XU, Chen [US/US]; c/o Enthone Inc., 600 Route 440, Jersey City, NJ 07304

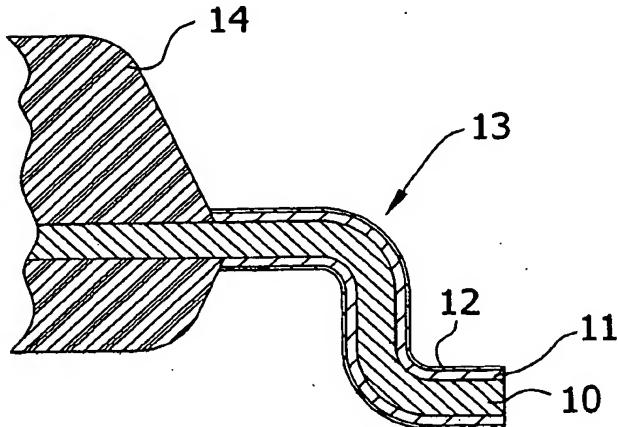
(US). ZHANG, Yun [US/US]; c/o Enthone Inc., 600 Route 440, Jersey City, NJ 07304 (US). FAN, Chonglun [CA/US]; c/o Enthone Inc., 600 Route 440, Jersey City, NJ 07304 (US). KHASALEV, Oscar [IL/US]; c/o Enthone Inc., 350 Frontage Road, New Haven, CT 06516 (US). ABYS, Joseph, A. [US/US]; c/o Enthone Inc., 350 Frontage Road, New Haven, CT 06516 (US). WALCH, Eric [DE/DE]; Buchner Strasse 31, 42699 Solingen (DE). KLEINFELD, Marlies [DE/DE]; Monhoffsfeld 142, 42369 Wuppertal (DE). ECKERT, Hans, Ullrich [DE/DE]; Hasencleverstrasse 21, 42659 Solingen (DE).

(74) Agents: FLEISCHUT, Paul, I.J. et al.; Senniger Powers, 1 Metropolitan Square, 16th Floor, St. Louis, MO 63102 (US).

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(54) Title: PRESERVING SOLDERABILITY AND INHIBITING WHISKER GROWTH IN TIN SURFACES OF ELECTRONIC COMPONENTS



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(57) Abstract: A method for reducing whisker formation and preserving solderability in tin coatings over metal features of electronic components. The tin coating has internal tensile stress and is between about 0.5 m and about 4.0 m in thickness. There is a nickel-based layer under the tin coating.



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